L Number	Hits	Search Text	DB	Time stamp
19	3785	134/57R,63,66,153,158,161,902.ccls.	USPAT;	2003/12/11 11:45
			US-PGPUB:	
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20	143	134/57R,63,66,153,158,161,902.ccls. and @pd>20030619	USPAT:	2003/12/11 11:46
i			US-PGPUB:	1000/12/11 11/10
			EPO; JPO;	
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21	124	(134/57R,63,66,153,158,161,902.ccls. and @pd>20030619)	USPAT:	2003/12/11 11:50
		and (semiconductor or wafer or substrate)	US-PGPUB:	
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22	49	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619)	USPAT:	2003/12/11 11:50
		and (semiconductor or wafer or substrate)) and (holder or	US-PGPUB;	2000/12/11 11:00
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23	87	118/52,53,500,501.ccls. and @pd>20030619	USPAT:	2003/12/11 11:56
		9.	US-PGPUB;	
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-	9	yuji.in. and kamikawa.in. and @pd>20030619	USPAT:	2003/12/04 10:19
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-	140	134/57R,63,66,153,158,161,902.ccls. and @pd>20030619	USPAT:	2003/12/04 10:20
			US-PGPUB:	
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			IBM TDB	
-	121	(134/57R,63,66,153,158,161,902.ccls. and @pd>20030619)	USPAT;	2003/12/04 10:21
		and (semiconductor or wafer or substrate)	US-PGPUB;	
	i		EPO; JPO;	
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			IBM_TDB	
-	67	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619)	USPAT;	2003/12/04 10:21
	1	and (semiconductor or wafer or substrate)) and (rotat\$3 or	US-PGPUB;	
		pivot\$3 or posture)	EPO; JPO;	
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-	85	118/52,53,500,501.ccls. and @pd>20030619	USPAT;	2003/12/04 12:01
	İ		US-PGPUB;	
			EPO; JPO;	
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